

# Earnings Conference for FY2026/3

---

2026/05/13

## TOKYO SEIMITSU CO., LTD.

**KIMURA Ryuichi, President and CEO**

**HOKIDA Takahiro, Director, Head of Semiconductor Company**

**ISHIKAWA Kazumasa, Executive Officer, Head of Metrology Company**

**KOIZUMI Kimito, Managing Executive Officer and CFO**

- **Cautionary Statement with respect to Forward-Looking Statements** : This presentation data and information verbally provided contain "forward-looking statements" that are based on current best available information and policies. There are various factors such as world economic conditions and semiconductor/automobile market conditions which will directly and indirectly impact the Company's results in the future. As a result, future outcomes may differ from those projected in this presentation.
- **Wordings and Data in presentation** : Unless otherwise noted, "SPE" denotes our Semiconductor Production Equip. Segment, "Metrology (or Metr.)" denotes our Metrology Equip. Segment, "Net profit" denotes Net profit attributable to owner of the parent, and "MTP" denotes Mid-Term business Plan.
- **About data**: Information listed in this presentation is summarized in Billions of Yen (JPY or B) or percentage except as otherwise noted. As a result, there may be a case where the total of individual amount and total amounts in each matter may differ.
- **Audit procedure**: This presentation is not subject to audit procedures.
- **Translation of the document**: This document has been translated from the Japanese original for reference purposes only. In the event of any discrepancy between this translated document and the Japanese original, the original shall prevail. The Company assumes no responsibility for this translation or for direct, indirect or any other forms of damages arising from the translation.

# Executive Summary

## FY2026/3 Results

- Sales reached ¥166.8B, YoY+11%, reached new record), Order was ¥163.1B(YoY +12%), driven by the HPC-related business in Semiconductor Production Equipment (hereinafter “SPE”) segment
- Net Profits remained flat YoY, Annual dividend to be ¥262/share (YoY +¥9)

## The MTP First FY Summary

- Proceed both “preparation for long-term growth” and “growth during the period” in optimum balance
- Promoted high-value Probers as an aspect for “Promoting growth of strategic products”
- Proceeded initiatives to expand production capacity

## FY2027/3 Forecast

- Both SPE and Metrology are expected to align with the premises of the MTP
- Strong demand for HPC and the expansion of value-added products contribute to increase sales and profits
- Profit margin growth is also expected

# FY2026/3 Full Year Results

Sales reached new record high, and Operating profit / Recutting profits also increased

Company-Wide results (BJPY)		FY2025/3	FY2026/3	VS. Forecast from Feb.	YoY
Orders		145.6	163.1	-	+12%
Sales		150.5	166.8	+1.8	+11%
Operating profit (OP)		29.7	33.7	+1.7	+14%
(OP Margin) (OPM)		(20%)	(20%)	-	+0pt
Recurring profit		29.9	34.8	+2.8	+16%
Net profit		25.6	24.7	+3.2	-4%
R&D		10.4	12.0	+0.0	+16%
Capex		10.2	11.1	-0.9	+8%
Depreciation		5.1	5.6	+0.1	+9%
Dividend per share (JPY)		253 Yen	262 Yen	+40 Yen	+9 Yen
Segment Results		FY2025/3	FY2026/3	VS. Forecast from Feb.	YoY
SPE	Orders	107.7	123.4	-	+15%
	Sales	113.5	127.9	+0.4	+13%
	OP	24.3	28.4	-	+17%
	(OPM)	(21%)	(22%)	-	+1pt
Metr.	Orders	37.9	39.7	-	+5%
	Sales	37.1	39.0	+1.5	+5%
	OP	5.4	5.3	-	-1%
	(OPM)	(15%)	(14%)	-	-1pt

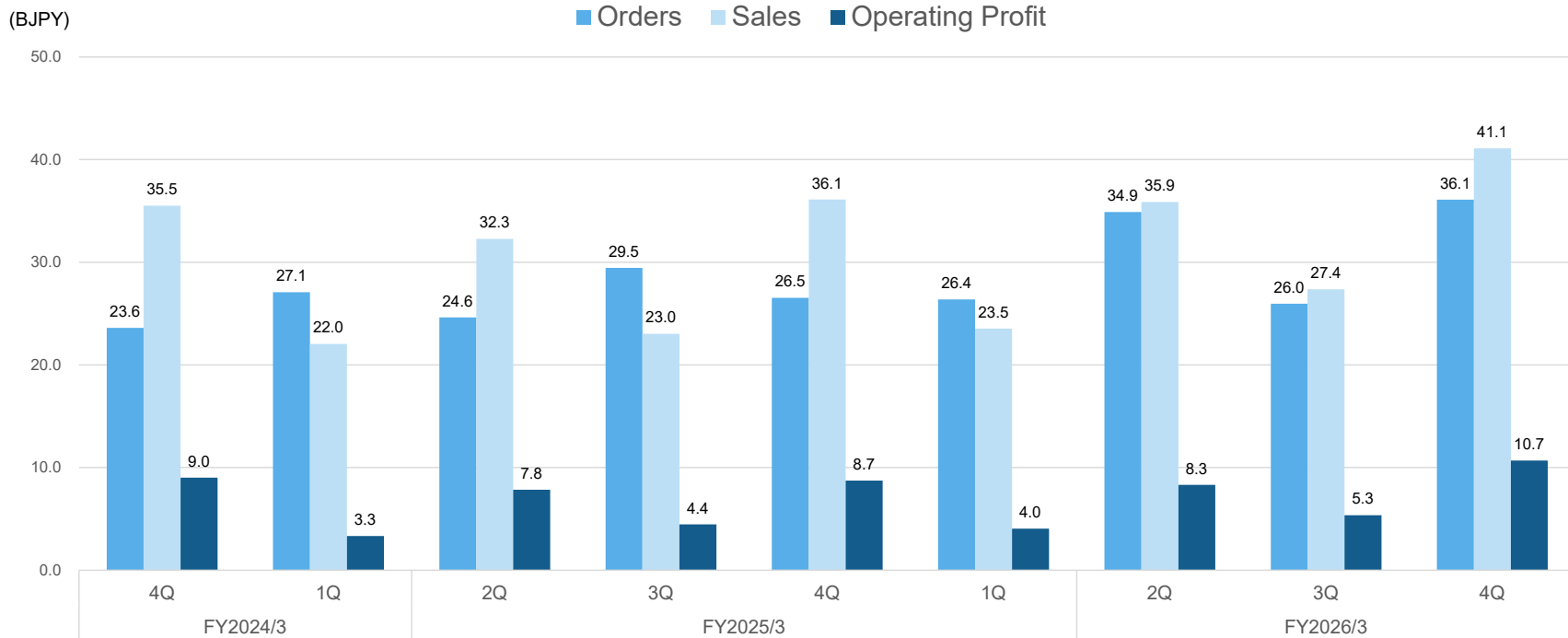
# FY2026/3 4Q Quarterly Results

Quarterly sales hit a new record high, and margin also increased

Company-Wide results (BJPY)		2023-1Q	2023-2Q	2023-3Q	2023-4Q	2024-1Q	2024-2Q	2024-3Q	2024-4Q	QoQ	YoY
Orders		37.4	33.7	39.2	35.3	35.9	44.7	36.6	45.8	+25%	+30%
Sales		29.6	41.8	31.7	47.4	30.9	46.2	35.9	53.9	+50%	+14%
Operating profit (OP)		4.1	9.3	5.7	10.6	4.6	10.1	6.2	12.8	+106%	+20%
(OP Margin) (OPM)		(14%)	(22%)	(18%)	(22%)	(15%)	(22%)	(17%)	(24%)	+7pt	+1pt
Recurring profit		4.3	8.8	6.6	10.1	4.5	10.5	6.7	13.1	+95%	+29%
Net profit		3.6	10.0	4.6	7.5	3.2	6.4	4.5	10.6	+133%	+41%
R&D		2.3	2.8	2.5	2.8	2.5	3.0	2.9	3.6	+21%	+29%
Capex		2.8	1.2	2.4	3.9	2.5	4.4	1.5	2.7	+78%	-31%
Depreciation		1.2	1.3	1.3	1.3	1.2	1.4	1.4	1.6	+7%	+13%
Segment Results		2023-1Q	2023-2Q	2023-3Q	2023-4Q	2024-1Q	2024-2Q	2024-3Q	2024-4Q	QoQ	YoY
SPE	Orders	27.1	24.6	29.5	26.5	26.4	34.9	26.0	36.1	+39%	+36%
	Sales	22.0	32.3	23.0	36.1	23.5	35.9	27.4	41.1	+50%	+14%
	OP	3.3	7.8	4.4	8.7	4.0	8.3	5.3	10.7	+101%	+23%
	(OPM)	(15%)	(24%)	(19%)	(24%)	(17%)	(23%)	(20%)	(26%)	+7pt	+2pt
Metr.	Orders	10.3	9.1	9.8	8.7	9.5	9.8	10.7	9.7	-9%	+12%
	Sales	7.6	9.5	8.7	11.3	7.3	10.3	8.5	12.8	+50%	+13%
	OP	0.8	1.5	1.2	1.9	0.5	1.8	0.9	2.1	+140%	+9%
	(OPM)	(10%)	(16%)	(14%)	(17%)	(7%)	(18%)	(10%)	(16%)	+6pt	-1pt

# SPE Segment Quarterly Trend

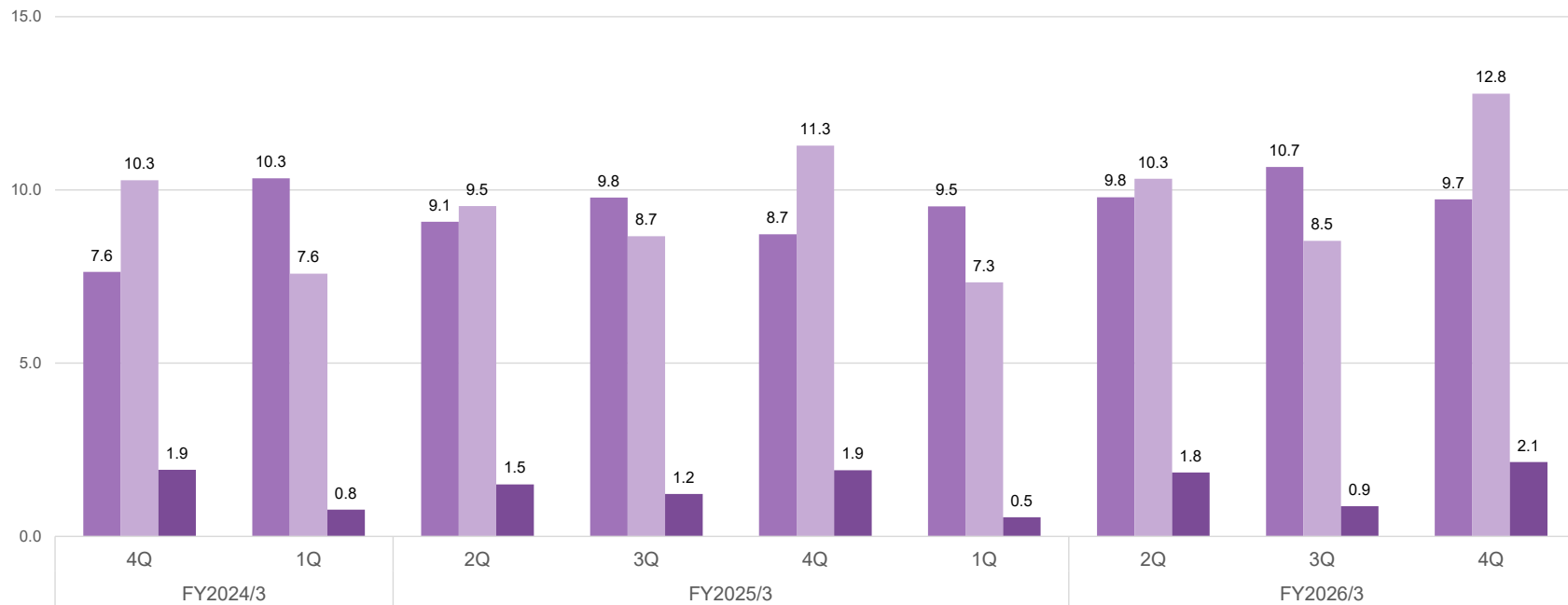
4Q orders were in line for the HPC and exceeded for other Non-HPC opportunities, Total orders slightly exceeded expectations, even with a partial adjustments in the order backlog (approx. ¥1.0B).



# Metrology Segment Quarterly Trend

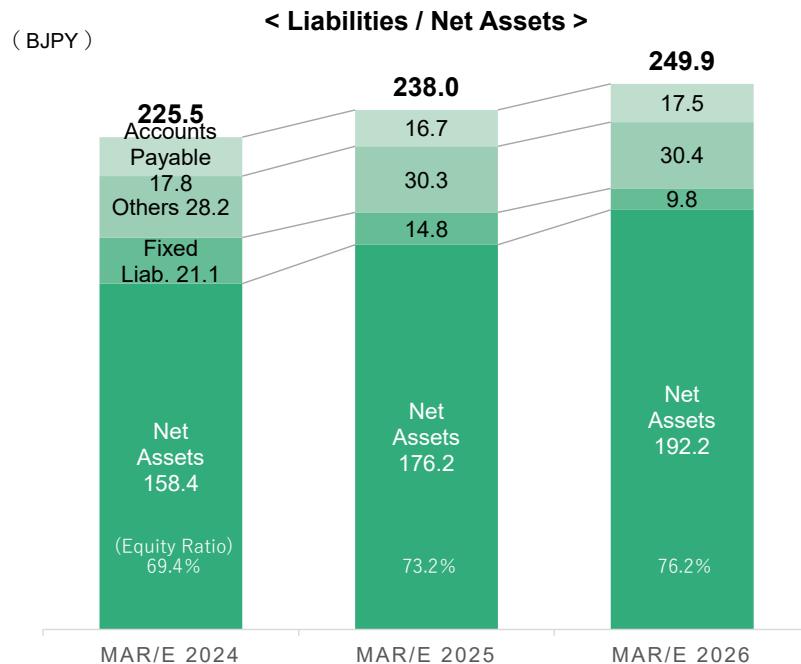
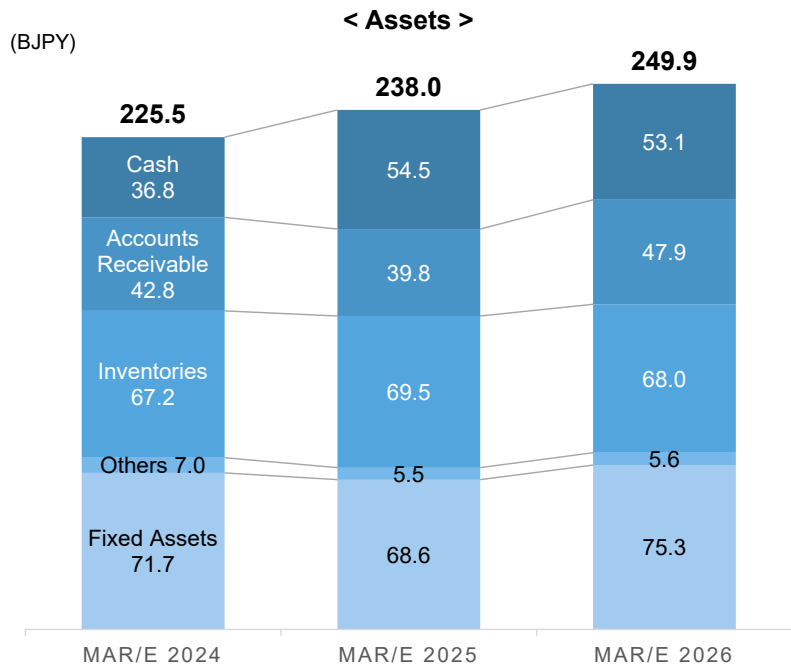
4Q orders exceeded company's outlook

(BJPY) Orders Sales Operating Profit



# Balance Sheet

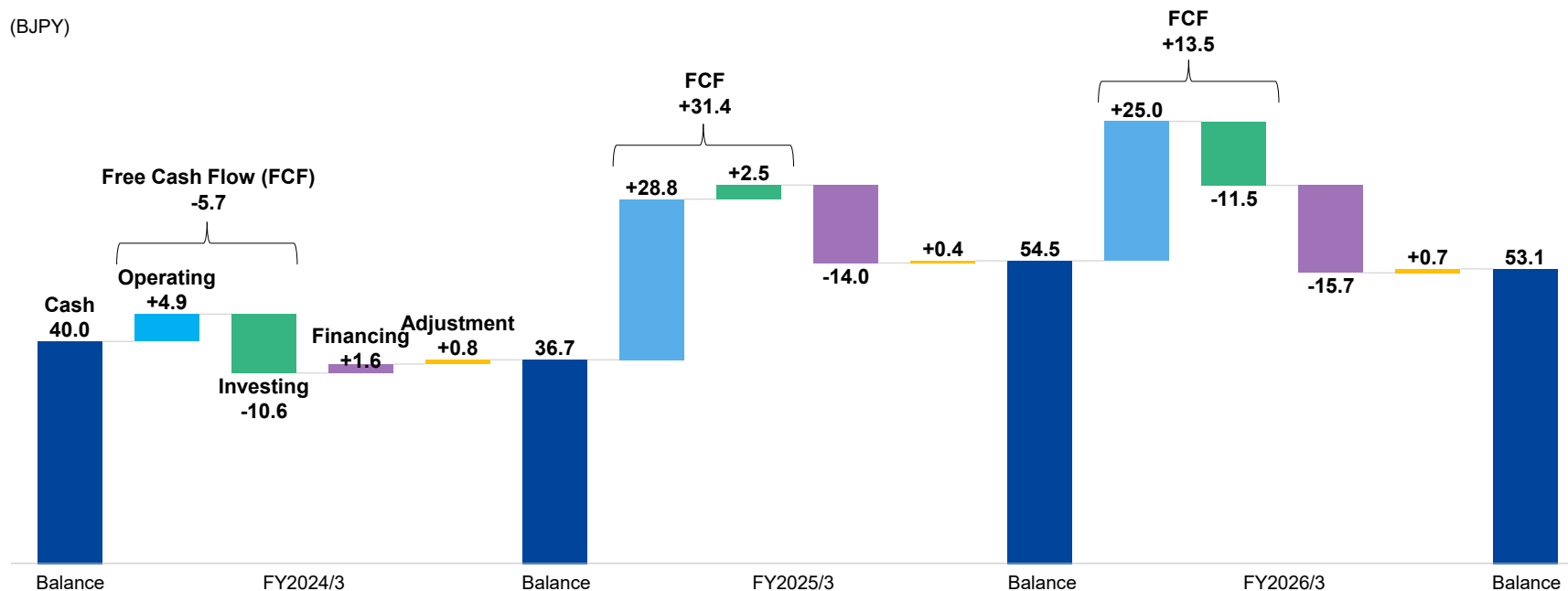
The fixed assets increased due to factory launch, as well as accounts receivable due to increase in sales



# Cash Flows

Operating cash flow has remained at a stable level, resulting in positive free cash flow

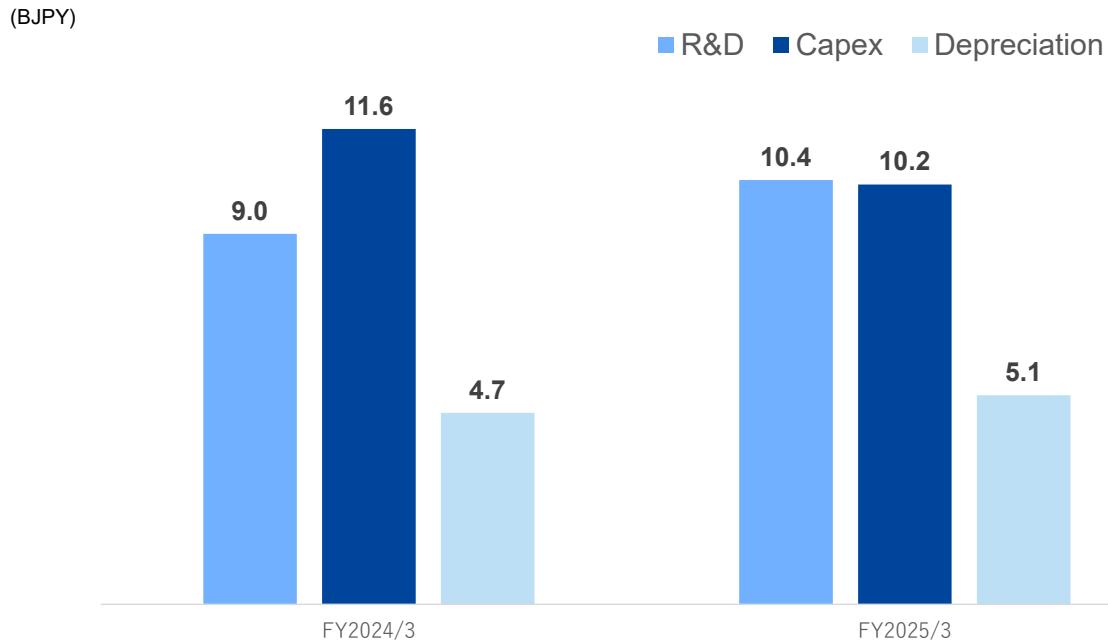
(BJPY)





# R&D, Capex and Depreciation

Capex was steadily implemented as an investment in future growth



## **FY2026/3-FY2028/3 MTP First Fiscal Year Summary**

# Positioning of the MTP (FY2026/3-FY2028/3)

The MTP (FY2026/3-FY2028/3) aims to achieve both “preparation for long-term growth” and “growth during the period.”



# Policy of the MTP (FY2026/3-FY2028/3)

Strengthening both the business and the business infrastructure itself

## Promoting growth of strategic products

- SPE :
  - Value-added Prober
  - High-end Grinding Machine
  - High-quality Dicer
- Metrology :
  - Battery testing systems
  - X-ray inspection system

## Pursuing technological synergies in metrology and SPE

- New SPEs with build-in of Metrology instruments
- Measuring application to Semis areas

## Strengthening recurring businesses

- SPE :
  - Strengthen service/supports
  - Expand consumable business
  - New business using existing equipment
- Metrology :
  - In-house testing services
  - Periodic calibration services

## Strengthening the business infrastructure to support these activities

Enhance Elemental technology development

Cross-segmental business strategy organisation

Environment that encourages new challenges

Improving productivity using IT

Evolution of sustainability management

# MTP (FY2026/3-FY2028/3) Quantitative Targets

Approx 20% increase in sales, 50% increase in Operating profits compared to FY2025/3 results have been set.

	FY2025/3 Results	Single FY during MTP period (FY2026/3-FY2028/3)
Sales	<b>¥150.5B</b> SPE ¥113.5B Metr. ¥37.1B	<b>¥185.0B</b> SPE ¥140.0B Metr. ¥45.0B
Operating Profit	<b>¥29.7B</b> SPE ¥24.3B Metr. ¥5.4B	<b>¥45.0B</b>
OP Margin	<b>20%</b> SPE 21% Metr. 15%	<b>24%</b>
ROE	<b>15%</b>	<b>15%</b>

## Premises

- Set as single-year targets (considering market volatility)
- SPE: Outperform the target market's CAGR assumption of +5%
- Metrology: Sustained recovery in market conditions for non-automotive (semis, aerospace, etc.)
- OP : Sales growth (including value-added products)  
Progress in gross cost reduction, promotion of recurring business
- ROE : Increase in net profit
- Risk Factors :
  - Uncertainty in consumer application demand
  - Geopolitical risks (China's equipment demand, competition, etc.)
  - Slowdown in machine tool orders

# MTP (FY2026/3-FY2028/3) - First FY Summary -

steadily implemented actions in line with our overall and basic policies

Promoting growth of  
strategic products

## **SPE : Strengthening the Development of High-Value-Added Products**

- High-precision temperature control probers ➡ Contributed capturing HPC-business
- Grinders for hybrid bonding, processing equipment for large PLPs, etc

## **Metrology : Enhancing the functionality and value of various instruments**

- High-end instruments → Capturing new demand in the aerospace and defense area
- Enhancing automation capabilities and strengthening services for charge/discharge testing systems

Pursuing technological  
synergies in metrology and  
SPE

## **Enhancing Solution Proposals**

- Expanding “Built-in Measurement” to Probers, Dicers, and Grinders
- Strengthening sales of Metrology equipment to semis and SPE sectors

Strengthening recurring  
businesses

## **Promotion of consumables sales and strengthening development**

- Strengthen the development and rollout of new consumables especially dicing blades

## **Expansion of service activities**

- Strengthen proposals for maintenance and equipment calibration services
- Establish a system management framework for recurring business

# Cash allocation - First FY Summary -

Steadily implemented investments aimed at future growth

## R&D

**Expect ¥35.0B-¥40.0B over 3 years through strengthening R&D**

Including development of strategic products, elemental technologies, synergy technology between Metrology and SPE, and Joint development with third parties .

→ **First FY investment: ¥12.0B**

**High-precision temperature-controlled probers;**

**Strengthening product capabilities for leading applications**

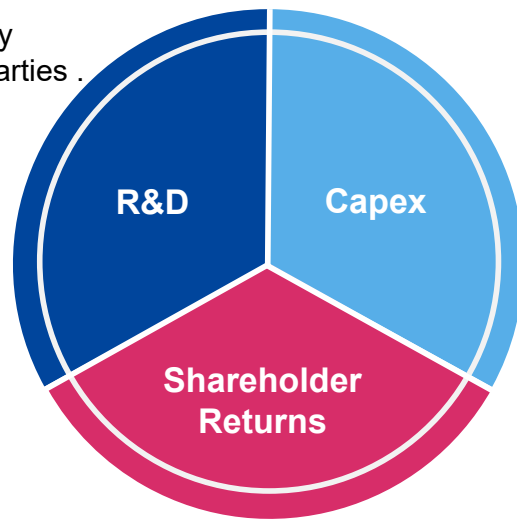
## Capex

**Except ¥30.0B-40.0B<sup>(\*)</sup> over 3 years with an eye of future**

- For growth : *Nagoya plant, Hachioji new plant, South Korea demo center, and battery testing services*
- For business base: IT, operational efficiency, and for ESG

→ **First FY investment: ¥11.1B**

**Nagoya Plant, Korea Demonstration Center, Rechargeable Battery Evaluation Center, and other investments as a part of MTP (new bldg near the Hanno Plant, new Hachioji Plant etc.)**



(\*) Subject to change due to construction progress

## **Forecast for FY2027/3**



# Premises of FY2027/3 Forecast

## Sales & Profits

**SPE : Revenue growth driven by HPC incl. gen. AI; expectations for memory and logic business, forecasts FY YoY increase**

- HPC-related including Gen.AI : Sales/profits contribution to rise (approximately to 40%)
- Global OSAT : Shipments of probers not limited to HPC but other Logics to increase
- China Demands : Maintain firm demand driven by high-end use
- Memory (Non-HBM) : Shipments for DRAM/NAND to increase

**Metr. : Increase YoY amid recover in industry, price revision, and businesses among aerospace, defense and semis**

**Profits : Although cost pressures remain, aim to move closer to MTP target through high-value products and other factors**

## Order Trend

**SPE : Except strong HPC and China biz + growth in memory and logic biz 1H (Although no plan for 2H, we expect firm tone)**

- HPC-related including Gen.AI : Except +20% HoH mainly driven by HBM business
- Global OSAT : Inquiries likely to increase
- China Demands : Solid demand remains mainly for high-end use
- Memory (Non-HBM) : Expect acceleration toward DRAM/NAND investments

**Metr. : Except an increasing opportunities among in aerospace, defense, semis, and also from subsidy-related business**

## FY2027/3 Forecast

Although 2H biz is expected to remain robust, the Company prepares fcst based on outlook that are reasonably achievable. Sales and profits are expected to increase, driven primarily by high-value-added SPE (probers)

Forex assumption: ¥150 / US\$ (Forex impact is minimal: High ratio of Yen-based businesses)

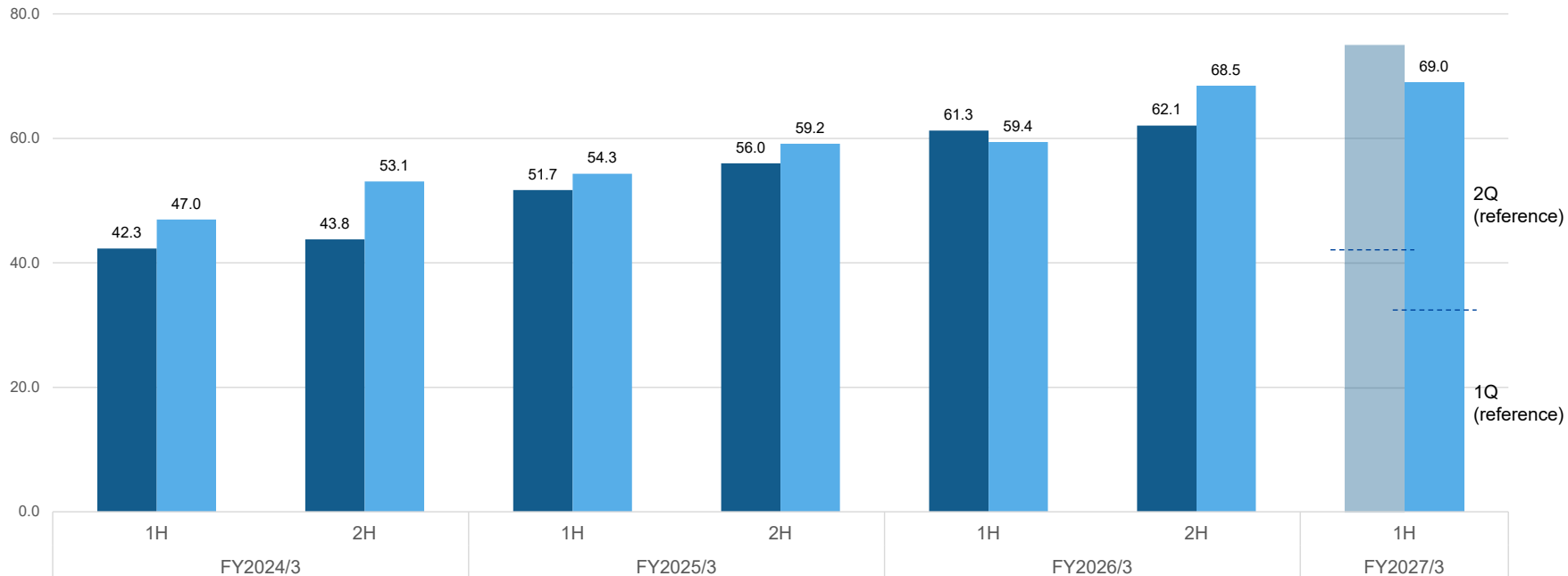
Company-Wide results (BJPY)	FY2026/3 1H	FY2026/3 2H	FY2026/3	FY2027/3 1H(f)	FY2027/3 2H(f)	FY2027/3(f)	YoY
Orders	80.6	82.5	163.1	-	-	-	-
Sales	77.1	89.8	166.8	87.5	94.0	181.5	+9%
Operating profit	14.7	19.0	33.7	18.7	21.3	40.0	+19%
(OP Margin)	(19%)	(21%)	(20%)	(21%)	(23%)	(22%)	+2pt
Recurring profit	15.0	19.9	34.8	18.7	21.3	40.0	+15%
Net profit	9.6	15.1	24.7	13.1	14.9	28.0	+13%
R&D	5.5	6.5	12.0	-	-	13.0	+8%
Capex	6.9	4.2	11.1	-	-	11.0	-1%
Depreciation	2.7	2.9	5.6	-	-	6.2	+11%
Segment Results	FY2026/3 1H	FY2026/3 2H	FY2026/3	FY2027/3 1H(f)	FY2027/3 2H(f)	FY2027/3(f)	YoY
SPE	59.4	68.5	127.9	69.0	72.5	141.5	+11%
Metr.	17.7	21.3	39.0	18.5	21.5	40.0	+3%
Dividend per share (JPY)	111	151	262	138	138	276	+14

# SPE Sales/Orders incl. Forecasts

FY2027/3 1H orders are expected to increase by approximately 20% HoH

(BJPY)

■ Orders ■ Sales

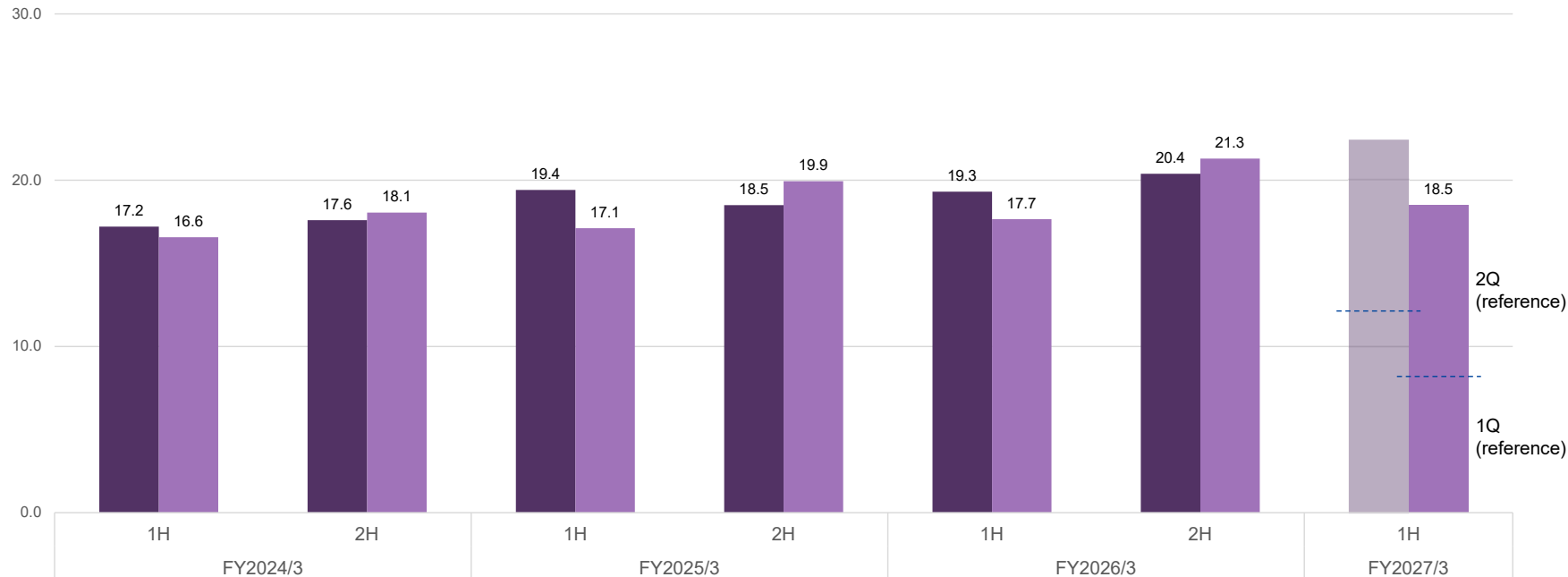


# Metrology Sales/Orders incl. Forecasts

FY2027/3 1H orders are expected to increase by approximately 10% HoH

(BJPY)

Orders Sales



## 質疑応答 / Q&A

# Supplementary Data - 生成AIを含むHPC / HPC-related business incl. Gen.AI

## <売上高/Sales>

(前半期比増減率 / HoH Changes)	2025年度上期 FY2026/3 1H	2025年度下期 FY2026/3 2H	2026年度上期予 FY2027/3 1H (f)
生成AIを含むHPC 全体 HPC-related incl. Gen. AI	前半期比 +55% HoH	前半期比 +32% HoH	前半期比 +18% HoH
うちロジック (生成AIを含む) of which Logic (incl. Gen AI)	前半期比 +81% HoH	前半期比 +11% HoH	前半期比 +1% HoH
うちHBM of which HBM	前半期比 +28% HoH	前半期比 +64% HoH	前半期比 +35% HoH
SPE売上高に占めるHPC関連の割合 HPC-related proportion of total SPE sales	30%強 / Low 30%	30%半ば / Mid-30%	40%強 / Low 40%

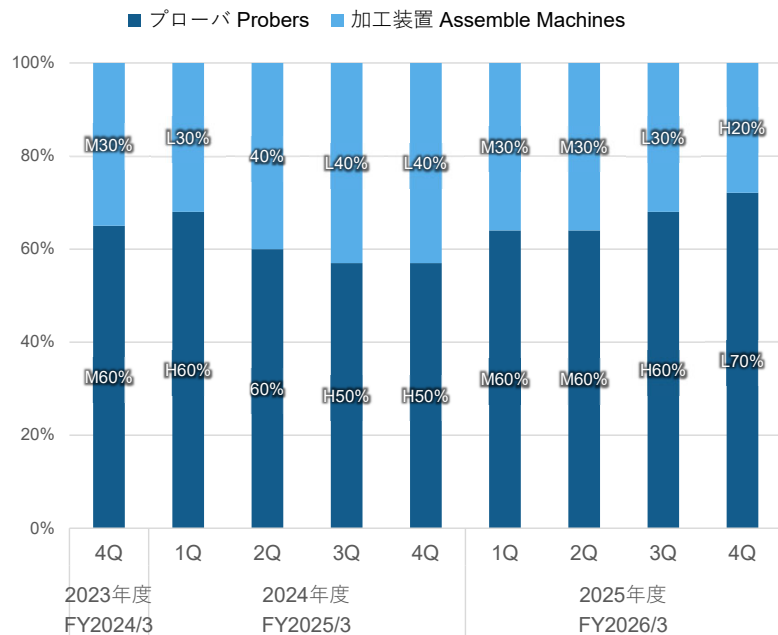
## <受注高/Orders>

(前半期比増減率 / HoH Changes)	2025年度上期 FY2026/3 1H	2025年度下期 FY2026/3 2H	2026年度上期予 FY2027/3 1H (f)
生成AIを含むHPC 全体 HPC-related incl. Gen. AI	前半期比 +24% HoH	前半期比 +4% HoH	前半期比 +15% HoH
うちロジック (生成AIを含む) (*) of which Logic (incl. Gen AI) (*)	前半期比 -11% HoH	前半期比 +84% HoH	前半期比 -16% HoH
うちHBM of which HBM	前半期比 +65% HoH	前半期比 -48% HoH	前半期比 +88% HoH
SPE受注高に占めるHPC関連の割合 HPC-related proportion of total SPE orders	40%	40%	40%強 / Low 40%

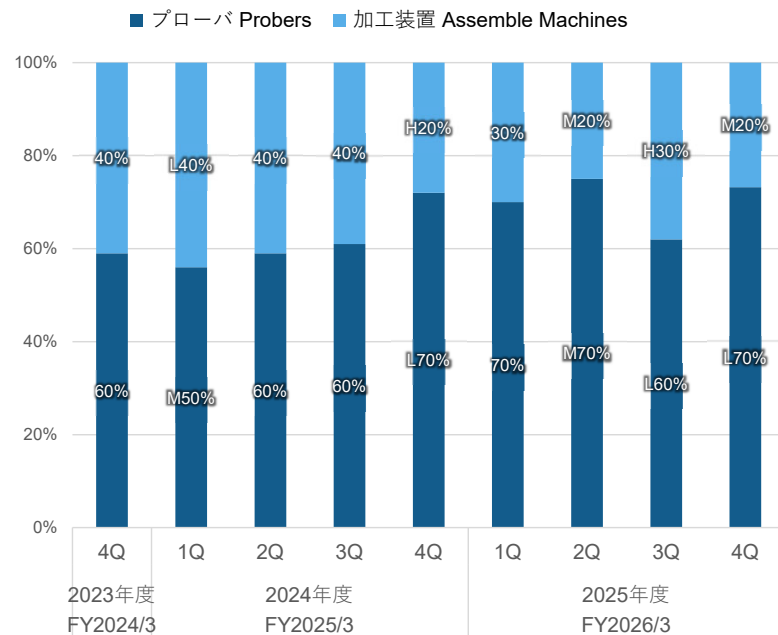
- 変動が大きいため、四半期別の開示は行っておりません。 Due to significant volatilities, the Company does not provide quarterly forecasts.
- 『生成AIを含むHPC全体』は、「うちロジック(生成AIを含む)」および「うちHBM」の合計です。「うちロジック(生成AIを含む)」には、ロジックデバイス向けプローバやAIパッケージング向けの加工装置の需要が含まれています。なお、当社は製品の特性上、検査や加工がおこなわれる半導体デバイスの種別を特定することが困難であることから、生成AIに限定した分類は行っておりません。“HPC-related incl. Gen.AI” represents the sum of ‘of which Logic (incl. Gen.AI)’ and ‘of which HBM’. The ‘of which Logic (incl. Gen. AI)’ encompasses businesses for probers for logic devices and assembly equipment for AI packaging. Note that due to the nature of our products, it is difficult to identify the specific types of semiconductor devices undergoing inspection or processing; consequently, the Company does not undertake classification limited solely to Generative AI.

# Supplementary Data - 製品別構成比 半導体 / SPE Segment per Product

<売上高 Sales>



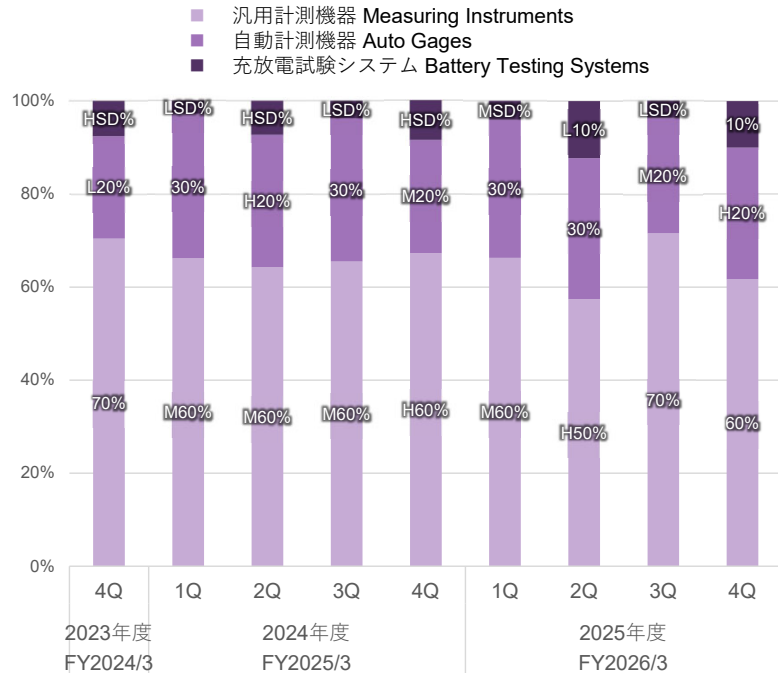
<受注高 Orders>



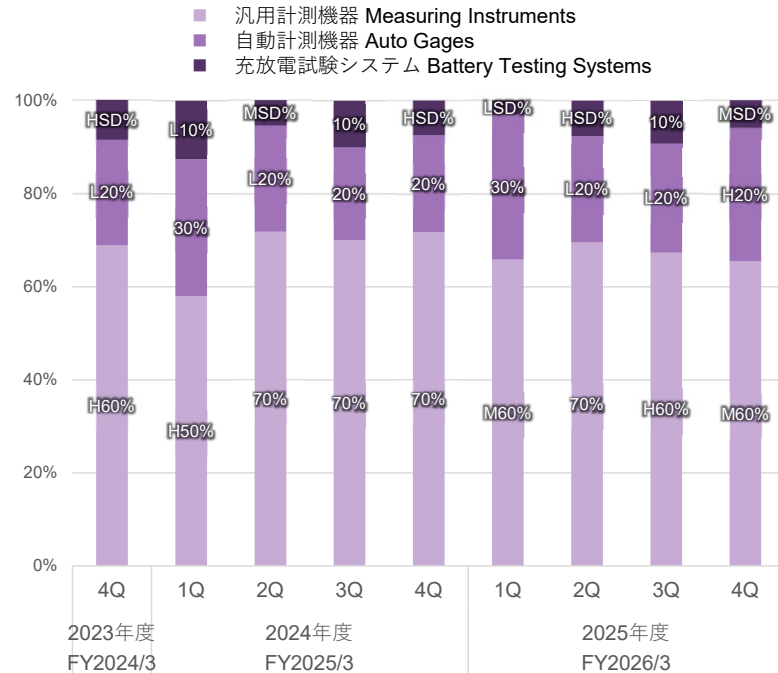
%表記：L:Low(前半), M:Middle(半ば), H:High(後半)、0-3%:LSD(Low Single Digit)、4-6%:MSD% (Mid Single Digit)、7-8%:HSD% (High Single Digit)

# Supplementary Data - 製品別構成比 計測 / Metrology Segment per Product

<売上高 Sales>



<受注高 Orders>

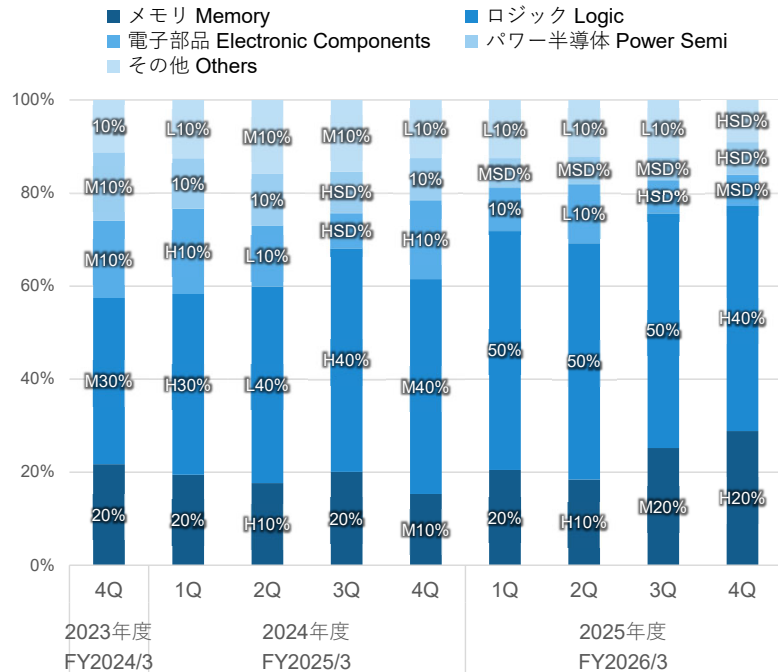


%表記 : L:Low(前半), M:Middle(半ば), H:High(後半)、0-3%:LSD(Low Single Digit)、4-6%:MSD% (Mid Single Digit)、7-8%:HSD% (High Single Digit)

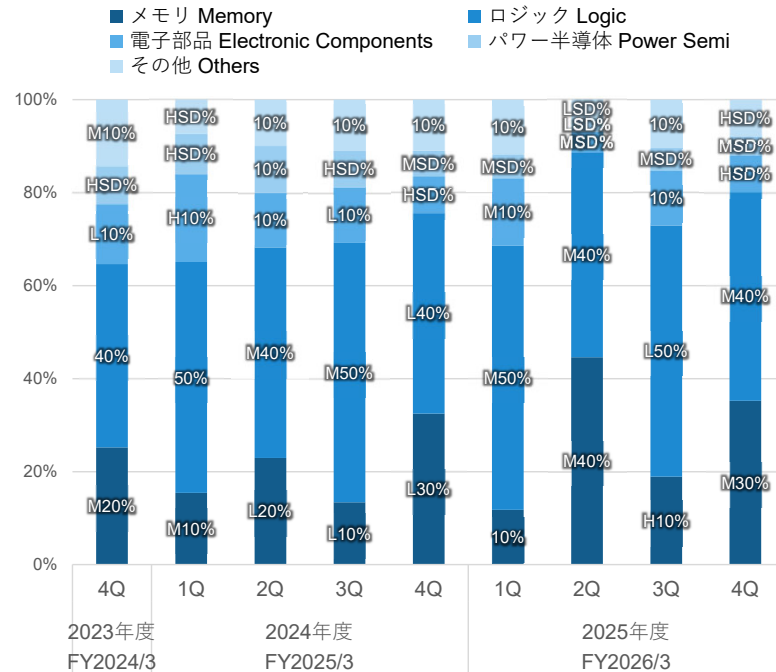


# Supplementary Data - アプリ別構成比 半導体 / SPE Segment per Application

<売上高 Sales>



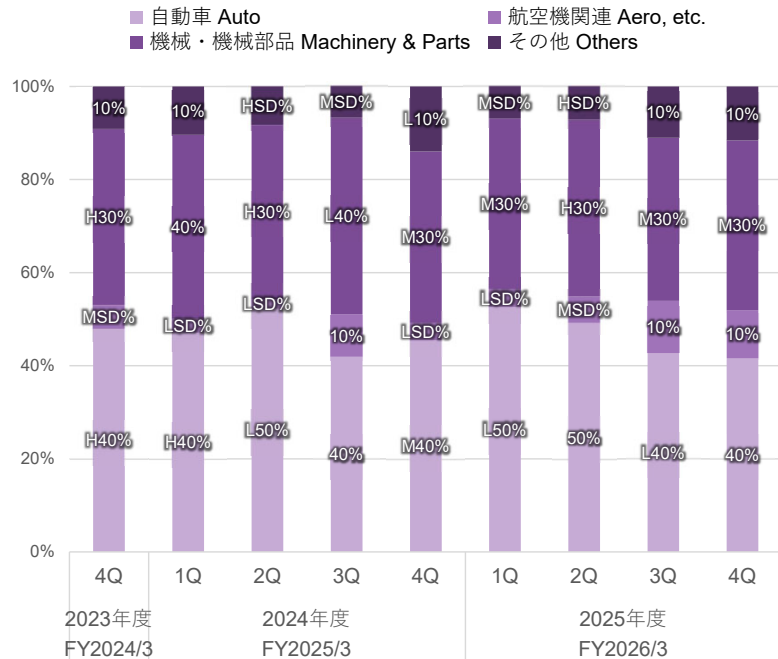
<受注高 Orders>



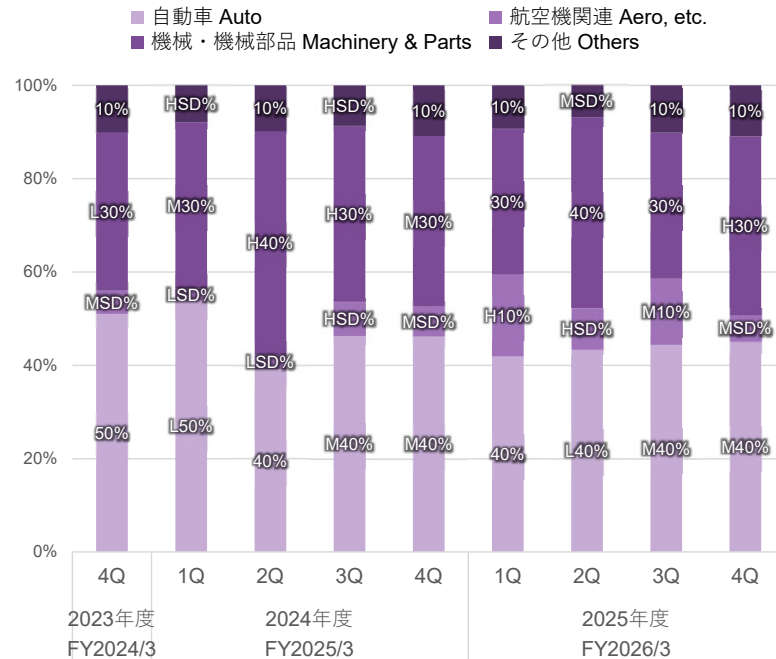
%表記 : L:Low(前半), M:Middle(半ば), H:High(後半)、0-3%:LSD(Low Single Digit)、4-6%:MSD% (Mid Single Digit)、7-8%:HSD% (High Single Digit)

# Supplementary Data - アプリ別構成比 計測 / Metrology Segment per Application

<売上高 Sales>



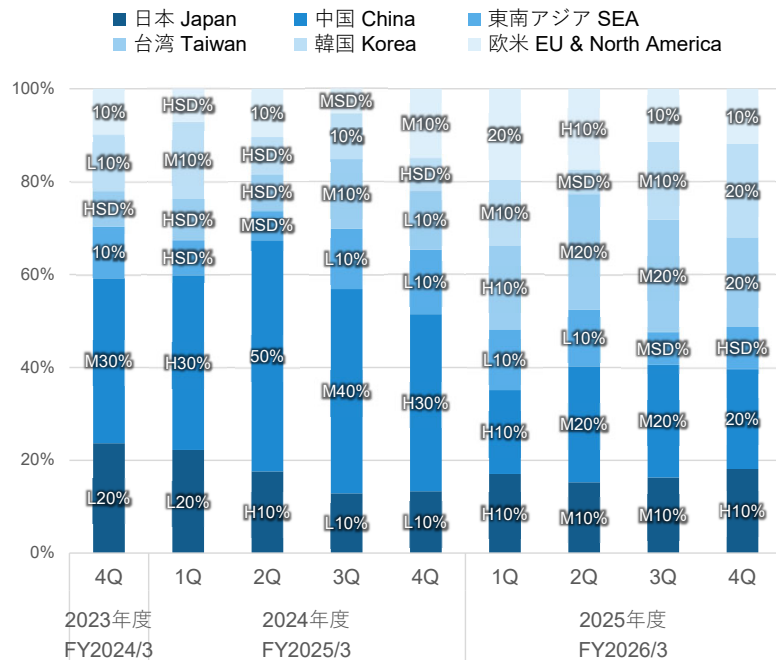
<受注高 Orders>



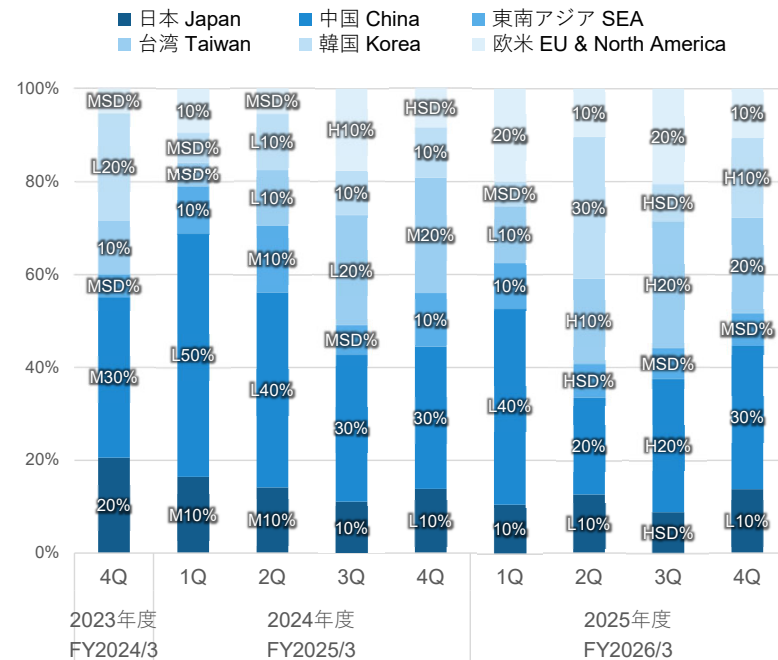
%表記 : L:Low(前半), M:Middle(半ば), H:High(後半)、0-3%:LSD(Low Single Digit)、4-6%:MSD% (Mid Single Digit)、7-8%:HSD% (High Single Digit)

# Supplementary Data - 地域別構成比 半導体 / SPE per Region

<売上高 Sales>



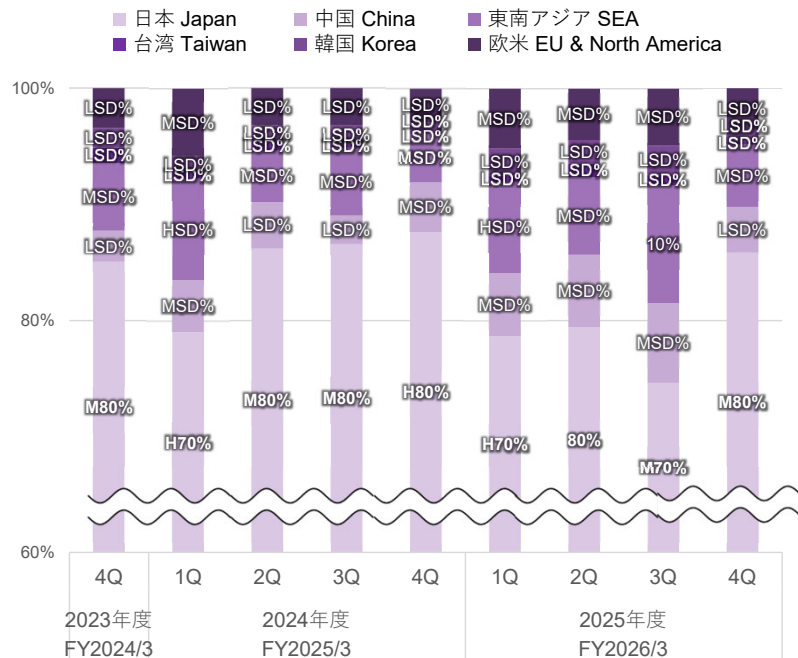
<受注高 Orders>



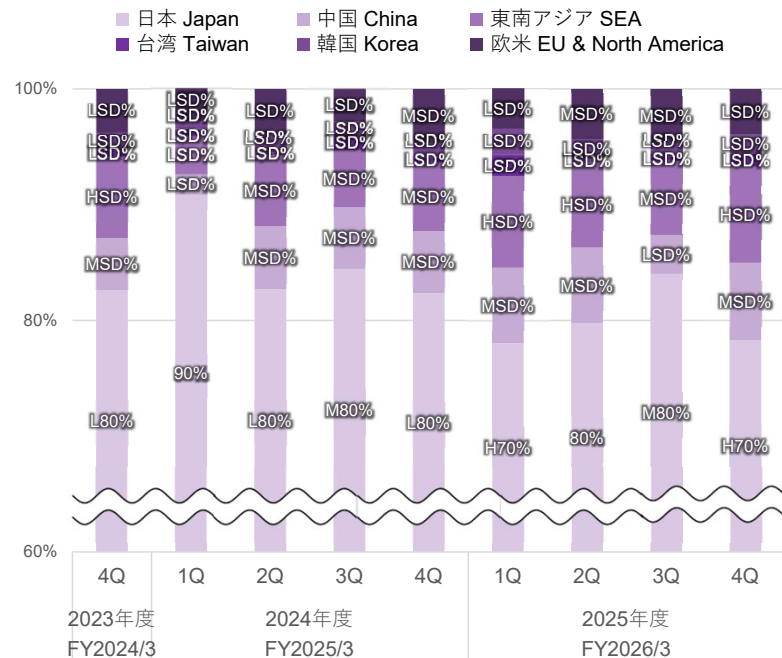
%表記 : L:Low(前半), M:Middle(半ば), H:High(後半)、0-3%:LSD(Low Single Digit)、4-6%:MSD% (Mid Single Digit)、7-8%:HSD% (High Single Digit)

# Supplementary Data - 地域別構成比 計測 / Metrology per Region

<売上高 Sales>



<受注高 Orders>



%表記: L:Low(前半), M:Middle(半ば), H:High(後半)、0-3%:LSD(Low Single Digit)、4-6%:MSD% (Mid Single Digit)、7-8%:HSD% (High Single Digit)

(注) 取引顧客の国籍による分類であり、日本向け売上高・受注高には、第3国への輸出案件が含まれています。This data classifies based on customers' nationality. Sales and orders for Japan include export transactions to third countries.

# Supplementary Data - セグメント別業績推移 / Segment

(百万円) Million Yen		会計期間 Fiscal Year				四半期 Quarter							
		2022年 3月期 FY2022/3	2023年 3月期 FY2023/3	2024年 3月期 FY2024/3	2025年 3月期 FY2025/3	2025年3月期 FY2025/3				2026年3月期 FY2026/3			
						1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
受注増	半導体 SPE	152,896	99,366	86,082	107,713	27,081	24,631	29,456	26,544	26,378	34,945	25,965	36,106
	計測 Metr.	33,159	36,960	34,802	37,917	10,336	9,082	9,781	8,717	9,523	9,786	10,661	9,728
	合計 Total	186,056	136,326	120,885	145,631	37,417	33,713	39,237	35,262	35,901	44,732	36,627	45,835
受注残高	半導体 SPE	102,370	89,371	75,398	69,630	80,433	72,785	79,205	69,630	72,466	71,541	70,134	65,149
	計測 Metr.	9,904	12,428	12,606	13,470	15,362	14,911	16,031	13,470	15,660	15,123	17,257	14,210
	合計 Total	112,274	101,799	88,004	83,101	95,796	87,697	95,236	83,101	88,127	86,664	87,391	79,359
売上高	半導体 SPE	101,145	112,365	100,055	113,481	22,046	32,280	23,036	36,118	23,542	35,870	27,372	41,092
	計測 Metr.	29,556	34,436	34,624	37,053	7,580	9,532	8,661	11,278	7,333	10,323	8,528	12,775
	合計 Total	130,702	146,801	134,680	150,534	29,626	41,812	31,698	47,397	30,876	46,194	35,900	53,867
営業利益	半導体 SPE	24,698	29,866	19,899	24,311	3,314	7,824	4,449	8,722	4,031	8,297	5,347	10,727
	計測 Metr.	3,628	4,628	5,408	5,392	768	1,497	1,220	1,905	549	1,838	867	2,077
	合計 Total	28,327	34,494	25,307	29,703	4,083	9,322	5,670	10,627	4,581	10,136	6,214	12,805
営業利益率	半導体 SPE	24.4%	26.6%	19.9%	21.4%	15.0%	24.2%	19.3%	24.1%	17.1%	23.1%	19.5%	26.1%
	計測 Metr.	12.3%	13.4%	15.6%	14.6%	10.1%	15.7%	14.1%	16.9%	7.5%	17.8%	10.2%	16.3%
	合計 Total	21.7%	23.5%	18.8%	19.7%	13.8%	22.3%	17.9%	22.4%	14.8%	21.9%	17.3%	23.8%

# Supplementary Data - 損益計算書 / Income Statement

(百万円) Million Yen	会計期間 Fiscal Year				四半期 Quarter							
	2022年 3月期 FY2022/3	2023年 3月期 FY2023/3	2024年 3月期 FY2024/3	2025年 3月期 FY2025/3	2025年3月期 FY2025/3				2026年3月期 FY2026/3			
					1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
売上高 Net Sales	130,702	146,801	134,680	150,534	29,626	41,812	31,698	47,397	30,876	46,194	35,900	53,867
売上原価 Cost of goods sold	77,694	84,967	79,917	88,081	17,753	24,757	17,960	27,609	18,468	27,411	21,063	31,034
売上総利益 Gross Profit on Sales	53,008	61,834	54,762	62,453	11,873	17,054	13,738	19,787	12,407	18,783	14,837	22,832
販売費および一般管理費 Selling, general and administrative expenses	24,681	27,339	29,454	32,750	7,790	7,732	8,067	9,159	7,825	8,647	8,622	10,026
営業利益 Operating profit	28,327	34,494	25,307	29,703	4,083	9,322	5,670	10,627	4,581	10,136	6,214	12,805
営業外収益 Non-operating income	987	965	1,404	921	287	39	539	55	133	309	609	428
営業外費用 Non-operating expenses	153	162	259	684	41	531	-422	534	252	-69	84	126
経常利益 Recurring Profit	29,160	35,297	26,453	29,939	4,329	8,829	6,632	10,148	4,462	10,515	6,739	13,108
特別利益 Extraordinary gains	390	103	824	4,493	10	4,483	0	0	3	85	105	0
特別損失 Extraordinary losses	34	2,099	21	158	-	-	157	0	-	2,103	-	-269
税引前利益 Profit before income taxes and minority interests	29,516	33,301	27,255	34,275	4,339	13,312	6,474	10,148	4,465	8,498	6,844	13,377
法人税等合計 Total Income tax and others	8,132	9,607	7,791	8,531	754	3,310	1,870	2,596	1,228	2,090	2,268	2,768
非支配株主に帰属する四半期純利益 Net Profit attributable to minority interests	57	62	84	106	31	6	29	39	7	25	39	18
親会社株主に帰属する当期純利益 Net Profit attributable to Owners of the Parent	21,326	23,630	19,378	25,637	3,554	9,996	4,574	7,512	3,229	6,382	4,536	10,590
1株当たり当期純利益(円) Net Profit per Share (Yen)	522.52	581.33	480.49	633.75	87.89	247.09	113.07	185.67	79.77	157.32	112.74	260.73
潜在株式調整後 1株当たり当期純利益(円) Net Profit per Share (diluted) (Yen)	517.51	575.62	475.42	628.31	-	-	-	-	-	-	-	-

# Supplementary Data - 貸借対照表 / Balance Sheet

(百万円) (Million Yen)		2023年3月期 FY2023/3	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3
流動資産 Current Assets	現金及び預金 Cash and cash equivalents	40,080	36,782	54,541	53,073
	売上債権※1 Accounts Receivable※1	43,403	42,801	39,809	47,877
	棚卸資産 Inventories	53,482	67,225	69,513	68,022
	その他 Others	7,005	7,022	5,477	5,634
	合計 Total	143,972	153,831	169,341	174,607
固定資産合計 Total Fixed Assets		65,060	71,693	68,610	75,309
総資産 Total Assets		209,032	225,524	237,952	249,917
流動負債 Current Liabilities	買入債務※2 Accounts Payable※2	22,359	17,845	16,665	17,529
	その他 Others	28,588	28,156	30,268	30,350
	合計 Total	50,947	46,002	46,933	47,879
固定負債合計 Total long-term liabilities		12,057	21,094	14,789	9,832
負債合計 Total Liabilities		63,004	67,097	61,723	57,712
純資産合計 Total Net Assets		146,028	158,427	176,229	192,205
負債・純資産合計 Total Liabilities and Net Assets		209,032	225,524	237,952	249,917
有利子負債合計 Total interest-bearing debt		14,191	25,171	20,084	14,713
自己資本比率 Equity Ratio(%)		69.0%	69.4%	73.2%	76.2%
自己資本利益率 ROE(%)		17.3%	12.9%	15.5%	13.6%

※1: 電子記録債権、契約資産を含む  
Incl. Electronically recorded monetary claims

※2: 電子記録債務を含む  
Incl. Electronically recorded obligations-operating

# Supplementary Data - 各種費用, キャッシュフロー/ Expenses and

(百万円) (Million Yen)	2023年3月期 FY2023/3	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3
研究開発費 R&D expenses	8,542	9,042	10,354	12,037
設備投資 Capex	9,725	11,602	10,245	11,069
減価償却費 (のれんの償却を除く) Depreciation (excl. Amortization of goodwill)	3,832	4,673	5,105	5,582

(百万円) (Million Yen)	2023年3月期 FY2023/3	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2025年3月期 FY2026/3
営業活動によるキャッシュフロー Cash flows from operating activities	1,000	4,892	28,824	25,012
投資活動によるキャッシュフロー Cash flows from investing activities	-8,421	-10,563	2,541	-11,491
フリーキャッシュフロー Free cash flows	-7,421	-5,671	31,365	13,520
財務活動によるキャッシュフロー Cash flows from financing activities	-2,174	1,616	-13,991	-15,674
現金及び現金同等物に係る換算差額等 Adjustments	625	755	404	689
現金及び現金同等物の期末残高 Cash and cash equivalents at the end of year	40,036	36,736	54,516	53,052

(人数) (# of People)	2023年3月期 FY2023/3	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3
正社員合計 Total regular employees	2,468	2,658	2,767	2,890
臨時従業員 年間平均雇用人員数 (※1) Average number of part-time employees, not included in the above figure	1,258	1,225	1,258	1,365
従業員合計 (※1) Number of employees	3,726	3,883	4,025	4,255

※1: 従前の補足資料では、臨時従業員数の期末の実数を表記しておりましたが、年間平均数に改めております。また従業員合計は、正社員合計人数と、期間平均臨時従業員数の単純合算です。  
In previous supplementary documents the number of temporary employees was given as the actual number at the end of each fiscal term. However, this has been revised to the average number for each period. Therefore, "Number of employees" is a simple sum of the total number of regular employees and the average number of temporary employees during the period.



# Supplementary Data - (Reference) FY2027/3 Tokyo Seimitsu Materiality

Blue: Changes in FY2027/3

Theme (Total 6)	Materiality (Total 23)
Contributing to the realization of an enriched society	Creation and provision of products that resolve social issues
	Contributing to semiconductor manufacturing that creates the future and enriches society
	Contributing to innovation in manufacturing through precision measurement
Promotion of business activities that contribute to the creation of a sustainable society	Reduction of greenhouse gas emissions in the value chain
	Creation and provision of products contributing to the global environment
	Optimization of environmental conservation and resource management
	Realization of a circular economy
	Advanced environmental management system
Maintaining and strengthening a corporate attitude that responds to the trust and confidence of stakeholders	Promoting of Sustainability in the Value Chain
	Securing product quality and stable supply, and enhancing customer support
	Promotion of stakeholder engagement
Creating a workplace where diverse people can work positively and energetically	<b>Respect for diverse perspectives and values</b>
	Creating a workplace where people can work in good health, both physically and mentally
	Improving employee engagement
Strengthening governance as the basis for fair corporate activities	Strengthening corporate governance
	Strengthening the compliance
	Promotion of risk management
Strengthening the business base	<b>Promotion of the human resource recruitment and development</b>
	Strengthening R&D capabilities
	Management and utilization of intellectual properties
	Promotion of digital transformations(DX)
	Creating a corporate culture that supports innovation
	Realization of sustainable and stable business management